SiJ470DP

RoHS

COMPLIANT

HALOGEN

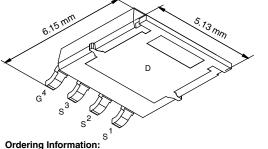
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N-Channel 100 V (D-S) MOSFET

PRODU	CT SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A) ^a	Q _g (Typ.)
100	0.0091 at V _{GS} = 10 V	58.8	28.5 nC
100	0.0100 at V _{GS} = 7.5 V	V _{GS} = 7.5 V 54.6	20.3 110

PowerPAK[®] SO-8L Single

SiJ470DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

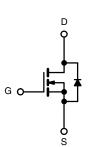


FEATURES

- ThunderFET[®] Technology Optimizes Balance of R_{DS(on)}, Q_g, Q_{sw} and Q_{oss}
- 100 % R_q and UIS Tested
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Primary Side Switching
- Synchronous Rectification
- DC/AC Inverters
- LED Backlighting
- High Current Switching



N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	100	N	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		58.8		
Continuous Drain Current (T. 150 °C)	T _C = 70 °C		47		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	17.4 ^{b, c}		
	T _A = 70 °C		13.9 ^{b, c}	•	
Pulsed Drain Current (t = 100 μs)		I _{DM}	150	— A	
Continuous Courses Ducia Dia da Cumant	T _C = 25 °C		51.6		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	4.5 ^{b, c}		
Single Pulse Avalanche Current	1 0.1 mll	I _{AS}	40		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	80	mJ	
	T _C = 25 °C		56.8		
Mauinum Davies Disaination	T _C = 70 °C		36.3		
Maximum Power Dissipation	T _A = 25 °C	P _D	5 ^{b, c}	W	
	T _A = 70 °C		3.2 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	•••	
Soldering Recommendations (Peak Temperature) ^{d, e}			260		

THERMAL RESISTANCE RATINGS Symbol Maximum Unit Parameter Typical Maximum Junction-to-Ambientb, f $t \le 10 s$ 25 **R**_{thJA} 20 °C/W Maximum Junction-to-Case (Drain) Steady State 1.8 2.2 R_{thJC}

Notes

- a. T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

- d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under steady state conditions is 65 °C/W.

S13-1672-Rev. /	Α,	29-Jul-13
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SiJ470DP

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	100	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$		-	63	-		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	- 7.2	-	mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2.3	-	3.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 100	nA	
Zava Cata Valtaga Duain Cuurant		V _{DS} = 100 V, V _{GS} = 0 V	-	-	1	μA	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$	-	-	10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	30	-	-	А	
Drain-Source On-State Resistance ^a	D	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	-	0.0076	0.0091		
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 7.5 \text{ V}, \text{ I}_{D} = 15 \text{ A}$	-	0.0083	0.0100	Ω	
Forward Transconductance ^a g_{fs} $V_{DS} = 10 \text{ V}, I_D = 20 \text{ A}$		$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	-	60	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	2050	-		
Output Capacitance	C _{oss}	V_{DS} = 50 V, V_{GS} = 0 V, f = 1 MHz	-	470	-	pF	
Reverse Transfer Capacitance	C _{rss}		-	40	-		
	0	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	36.9	56		
Total Gate Charge	Qg		-	28.5	43		
Gate-Source Charge	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 20 \text{ A}$	-	7.9	-	nC	
Gate-Drain Charge	Q _{gd}		-	9.2	-		
Output Charge	Q _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$	-	52	80		
Gate Resistance	Rg	f = 1 MHz	0.5	1.35	2.2	Ω	
Turn-On Delay Time	t _{d(on)}		-	12	24		
Rise Time	tr	V_{DD} = 50 V, R_L = 2.5 Ω	-	8	16	1	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 20$ Å, $V_{GEN} = 10$ V, $R_g = 1 \Omega$	-	22	24		
Fall Time	t _f		-	7	14		
Turn-On Delay Time	t _{d(on)}		-	13	26	ns	
Rise Time	tr	V_{DD} = 50 V, R_L = 2.5 Ω	-	12	24		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 20$ Å, $V_{GEN} = 7.5$ V, $R_g = 1 \Omega$	-	22	44		
Fall Time	t _f		-	8	16		
Drain-Source Body Diode Characteristic	S					1	
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	-	-	51.6		
Pulse Diode Forward Current (t = 100 µs)	I _{SM}		-	-	150	A	
Body Diode Voltage	V _{SD}	I _S = 5 A	-	0.76	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}		-	44	85	ns	
Body Diode Reverse Recovery Charge	Q _{rr}		-	67	130	nC	
Reverse Recovery Fall Time	$I_{\rm E} = 10$ A. dl/dt = 100 A/us.		-	27	-		
Reverse Recovery Rise Time	t _b		-	17	- I	ns	

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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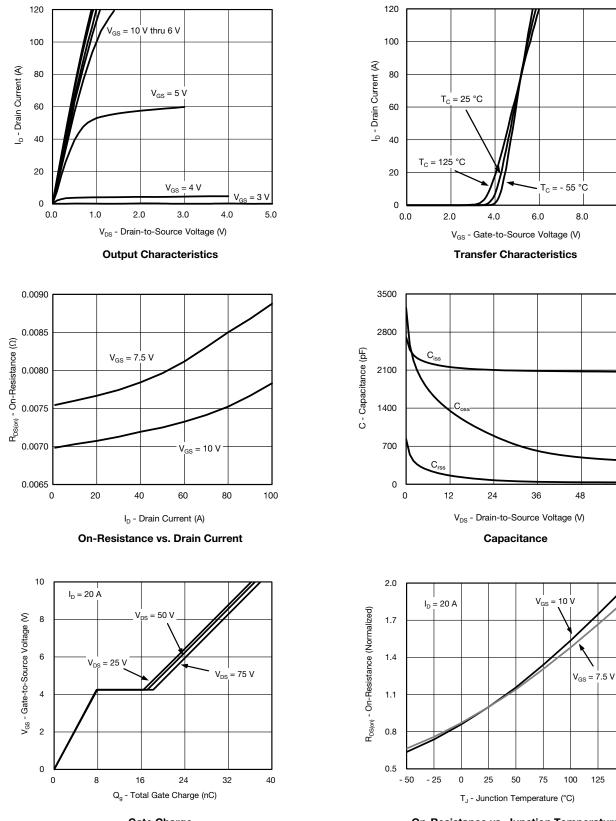


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Gate Charge

On-Resistance vs. Junction Temperature

S13-1672-Rev. A, 29-Jul-13

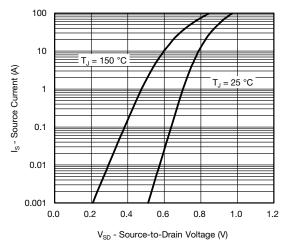
3 For technical questions, contact: <u>pmostechsupport@vishay.com</u> Document Number: 62883

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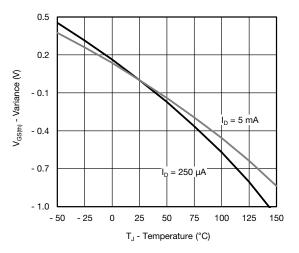
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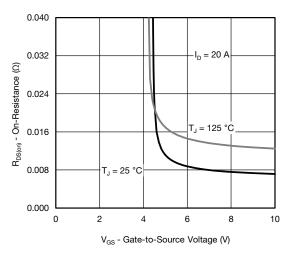
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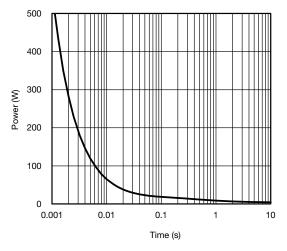
Source-Drain Diode Forward Voltage



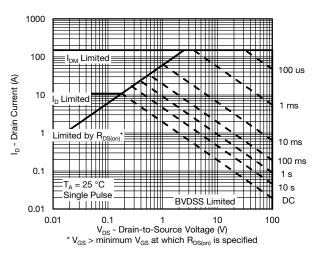
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

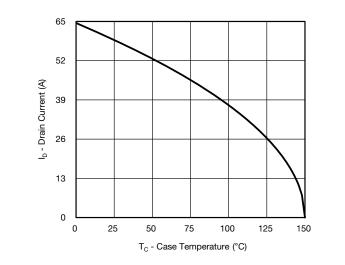


Safe Operating Area, Junction-to-Ambient

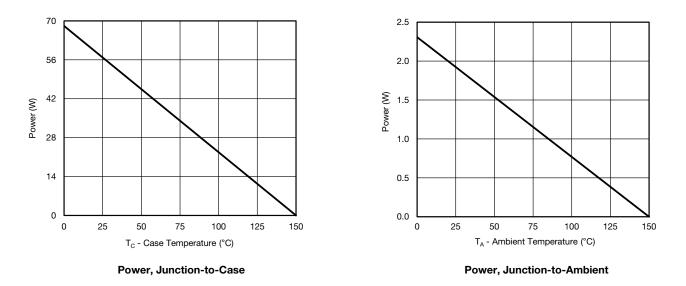
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



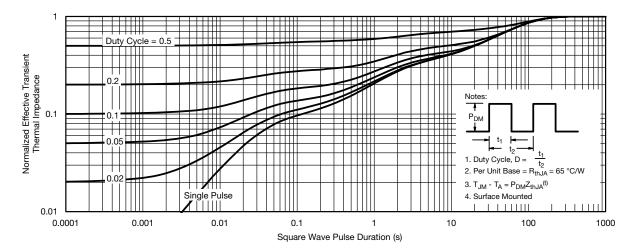
Current Derating*



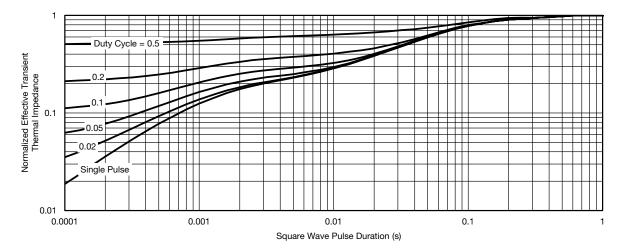
* The power dissipation P_D is based on T_{J(max.)} = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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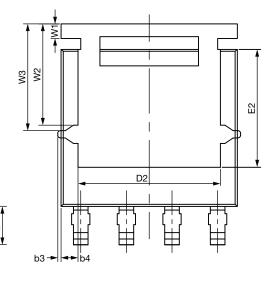


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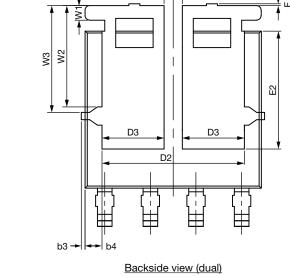
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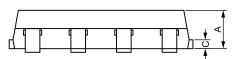




Topside view

Backside view (single)





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Package Information



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DIM.		MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
А	1.00	1.07	1.14	0.039	0.042	0.045		
A1	0.00	-	0.127	0.00	-	0.005		
b	0.33	0.41	0.48	0.013	0.016	0.019		
b1	0.44	0.51	0.58	0.017	0.020	0.023		
b2	4.80	4.90	5.00	0.189	0.193	0.197		
b3		0.094			0.004			
b4		0.47			0.019			
С	0.20	0.25	0.30	0.008	0.010	0.012		
D	5.00	5.13	5.25	0.197	0.202	0.207		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.86	3.96	4.06	0.152	0.156	0.160		
D3	1.63	1.73	1.83	0.064	0.068	0.072		
е		1.27 BSC		0.050 BSC				
E	6.05	6.15	6.25	0.238	0.242	0.246		
E1	4.27	4.37	4.47	0.168	0.172	0.176		
E2	3.18	3.28	3.38	0.125	0.129	0.133		
F	-	-	0.15	-	-	0.006		
L	0.62	0.72	0.82	0.024	0.028	0.032		
L1	0.92	1.07	1.22	0.036	0.042	0.048		
К		0.51			0.020			
W		0.23		0.009				
W1	0.41		0.016					
W2		2.82		0.111				
W3		2.96		0.117				
θ	0°	-	10°	0°	-	10°		

Note

• Millimeters will gover



RECOMMENDED MINIMUM PAD FOR PowerPAK[®] SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)

Revision: 07-Feb-12



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